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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Guoqiang Xing, et al.

Docket No: TI-31729

Serial No: 09/901,416

Conf. No: 7304

Examiner: Thanh T. Nguyen

Art Unit: 2814

Filed: 07/09/2001

For: DUAL HARMASK PROCESS FOR THE FORMATION OF COPPER/LOW-K
INTERCONNECTS

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TECHNOLOGY CENTER 2800
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AMENDMENT UNDER 37 C.F.R. § 1.111

Assistant Commissioner For Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(a)
I hereby certify that the above correspondence is being
deposited with the U.S. Postal Service with sufficient postage
as First Class Mail in an envelope addressed to: Assistant
Commissioner for Patents, Washington, DC 20231 on
12-10-02.

Ann Trent
Ann Trent

Dear Sir:

Responsive to the Office Action mailed September 10, 2002, in connection with
the above identified application, Applicants respectfully submit the following
amendments and remarks.